

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1-5. (Cancelled)

6. (Currently amended) A recycling method for recycling waste particles, ~~as a material to be melted or mixed, a cake that is obtained by comprising:~~

~~solidifying particle generated at a step of machining a crystal ingot into a wafer[,]~~ or at a step of machining a semiconductor wafer;

solidifying into a cake, particles generated by machining the crystal ingot or the semiconductor wafer; and

melting the cake.

7. (Currently amended) A recycling method for recycling waste particles ~~employing as a material to be melted, a cake that is obtained by solidifying particle generated at a step of comprising:~~

~~machining a crystal ingot into a wafer[,]~~ or ~~at a step of machining a semiconductor wafer;~~

solidifying into a cake, particles generated by machining the crystal ingot or the semiconductor wafer; and for

recycling said cake as an ingot.

8. (Currently amended) A recycling method for recycling waste particles ~~employing as a material to be melted, a cake that is obtained by solidifying, at a predetermined water content, particles generated at a step of comprising:~~

machining a crystal ingot into a wafer[,] or ~~at a step of~~ machining a semiconductor wafer;[,]

solidifying into a cake at a predetermined water content, particles generated by machining the crystal ingot or the semiconductor wafer; and for melting said cake recycling to recycle said cake as an ingot.

9. (Currently amended) A method for fabricating a semiconductor ingot ~~wherein a cake that is obtained by solidifying, at a predetermined water content and without a reaction with a chemical occurring, particles generated at a step of~~ comprising:

machining a crystal ingot into a wafer[,] or ~~at a step of~~ machining a semiconductor wafer; ~~is employed as a material to be melted~~

solidifying into a cake at a predetermined water content and without any chemical reactions, particles generated by machining the crystal ingot or the semiconductor wafer; and melting said cake.

10. (Currently amended) A recycling method according to one of claims 6 to 8, wherein said machining step ~~is an~~ comprises abrading, grinding or polishing, dicing, back grinding or wafer polishing step.

11. (Currently amended) A method according to claim 9, wherein said machining step ~~is an~~ comprises abrading, grinding or polishing, dicing, back grinding or wafer polishing step.

12- 18. (Cancelled)

19. (New) A method for processing particles comprising:
solidifying into a cake, particles that are generated by machining a crystal ingot into a wafer or machining a semiconductor wafer; and
melting the cake into an ingot.

20. (New) A method according to claim 19, further comprising:
solidifying said particles at a predetermined water content, without any chemical reactions.
21. (New) A method according to claim 19, wherein machining comprises abrading, grinding or polishing.
22. (New) A method according to claim 19, wherein machining said semiconductor wafer comprises dicing, back grinding or wafer polishing.
23. (New) A method according to claim 19, wherein said particles comprises Si flakes.
24. (New) A recycling method for recycling waste particles, comprising:
melting a cake which is produced by solidifying particles generated by machining a crystal ingot into a wafer or machining a semiconductor wafer.
25. (New) A recycling method for recycling waste particles comprising:
melting a cake to recycle the cake as an ingot, said cake produced by solidifying particles generated by machining a crystal ingot or a semiconductor wafer at a predetermined water content.
26. (New) A method for fabricating a semiconductor ingot comprising:
melting a cake which is produced by solidifying particles generated by machining a crystal ingot or a semiconductor wafer at a predetermined water content and without any chemical reactions.
27. (New) A method for processing particles comprising:
melting a cake into an ingot, said cake produced by solidifying particles that are generated by machining a crystal ingot into a wafer or machining a semiconductor wafer.